

LEADED

# BGA SOLDER PASTE

● ● ●  
Sn63/Pb37

Melting point 183°C



## Product Usage

### TIN PASTE

Type number	BST-503-JP
Types of	Solder Paste
Composition	Sn63/Pb37
Melting point	183°C
G.W.	70g
size	1.41*1.28 in



Sn63/Pb37

Melting point at medium temperature

183°C



**BEST**  
倍思特  
SOLDER PASTE

MODEL: BST-503-J  
Alloy: Sn63/Pb37  
Shelf Life: 6 months  
Weight: 70g  
MADE IN CHINA

**BEST**  
倍思特  
SOLDER PASTE

MODEL: BST-503-JP  
Alloy: Sn63/Pb37  
Shelf Life: 6 months  
Weight: 70g  
MADE IN CHINA

183°C

中温锡膏



**BEST**  
倍思特  
SOLDER PASTE

MODEL: BST-503-JP  
Alloy: Sn63/Pb37  
Shelf Life: 6 months  
Weight: 70g  
MADE IN CHINA

183°C

中温锡膏



Low residue



Solder spot bright



Rapid welding

# Welding requirements for a wide range of products



SMT  
patch



LED  
patch



BGA  
welding



# Product List

G.W.:70g



1.28 in (32mm)



1.42 in (36mm)